

ABSTRACT

The present invention relates to a surface property measuring apparatus for a polishing pad used for polishing a substrate, such as a semiconductor wafer, a surface property measuring method for a polishing pad, and a surface property judging method
5 for a polishing pad. The surface property measuring apparatus (30) includes: a light-emitting structure (32) configured to irradiate the polishing pad (2) with light from a plurality of directions as viewed from a polishing surface (2a) of the polishing pad (2); and a light-receiving structure (32) configured to receive reflected light traveling in a plurality of directions from the surface of the polishing pad (2).

Figure 15